

9/26/03  
SOG

L Number	Hits	Search Text	DB	Time stamp
1	1333	257/678 ccls. or 257/690.ccls.	USPAT	2003/09/26 14 05
2	407	((lead adj frame) with (etch\$3)) and (encapsul\$5)	USPAT	2003/09/26 15 08
3	1	("6420779").PN.	USPAT	2003/09/26 14 14
4	374	((lead adj frame) with (etch\$3)) and (encapsul\$5)) not (2003.ay. or 2002.ay. or 2001.ay.)	USPAT	2003/09/26 15 24
5	1497	257/672 ccls. or 257/673.ccls. or 257/674.ccls. or 257/676 ccls. or 257/677.ccls.	USPAT	2003/09/26 15 13
6	1378	(257/672.ccls. or 257/673.ccls. or 257/674.ccls. or 257/676 ccls. or 257/677.ccls.) not (2003.ay. or 2002.ay. or 2001.ay )	USPAT	2003/09/26 15 25
-	35	chip adj paddle	USPAT	2003/09/25 19 40
-	49	chip adj paddle	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/10/19 21 03
-	128	die adj receiving adj area	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/10/19 21 04
-	49	(die adj receiving adj area) and (etch or etched or etching)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/10/19 21 04
-	3	(die adj receiving adj area) with (etch or etched or etching)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/10/19 21 04
-	1977	257/666 ccls. or 257/667.ccls. or 257/670.ccls. or 257/672.ccls. or 257/673.ccls. or 257/674.ccls. or 257/676 ccls. or 257/677.ccls.	USPAT	2002/04/23 19 47
-	546	257/678.ccls.	USPAT	2002/04/23 19 20
-	1781	257/678 ccls. or 257/690 ccls. or 257/787.ccls	USPAT	2002/04/23 19 47
-	1366	(257/678.ccls. or 257/690.ccls. or 257/787.ccls.) not (257/666.ccls. or 257/667.ccls. or 257/670.ccls. or 257/672 ccls. or 257/673.ccls. or 257/674.ccls. or 257/676 ccls. or 257/677.ccls.)	USPAT	2002/04/23 19 48
-	1657	MEMS	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/04/25 17 32
-	1572	257/666 ccls. or 257/667 ccls. or 257/670.ccls.	USPAT	2003/09/25 20 15
-	1	("6501156").PN.	USPAT	2003/09/25 20 29
-	1	("5528076").PN.	USPAT	2003/09/25 20 15
-	2	("6211462") or ("6437429").PN.	USPAT	2003/09/25 21 52
-	5325	((lead or leads) with (etch or etched or etching or etches)) and (semiconductor or (integrated adj circuit))	USPAT	2003/09/25 21 52
-	72	((lead or leads) with (etch or etched or etching or etches)) and (semiconductor or (integrated adj circuit))) and ((die adj paddle) or (chip adj paddle))	USPAT	2003/09/25 21.53